



DATA SHEET

ANTI-SULFURATED CHIP RESISTORS

AF series 5%, 1% sizes 0201/0402/0603/0805/1206/1210/1218/2010/2512 RoHS compliant & Halogen free

Product specification – September 27, 2013 V.I



YAGEO Phicomp

Chip Resistor Surface Mount | AF | SERIES | 0201 to 2512

<u>SCOPE</u>

This specification describes AF0201 to AF2512 chip resistors with anti-sulfuration capabilities.

APPLICATIONS

- Industrial Equipment
- Power Application
- Networking Application
- High-end Computer & Multimedia Electronics in high sulfur environment

FEATURES

- Superior resistance against sulfur containing atmosphere
- Halogen free product and production
- RoHS compliant
 Products with lead free terminations most Bold
 - terminations meet RoHS requirements - Pb-glass contained in electrodes,
 - resistor element and glass are exempted by RoHS
- Reduces environmentally hazardous waste
- High component and equipment reliability
- Saving of PCB space
- Moisture sensitivity level: MSL I

ORDERING INFORMATION - GLOBAL PART NUMBER

Part number is identified by the series name, size, tolerance, packaging type, temperature coefficient, taping reel and resistance value.

GLOBAL PART NUMBER

AF XXXX X X X XX XXXX L

(1) (2) (3) (4) (5) (6) (7)

(I) SIZE

0201/0402/0603/0805/1206/1210/1218/2010/2512

(2) TOLERANCE

 $F = \pm 1\%$

 $J = \pm 5\%$

(3) PACKAGING TYPE

R = Paper taping reel

K = Embossed plastic tape reel

(4) TEMPERATURE COEFFICIENT OF RESISTANCE

– = Base on spec

(5) TAPING REEL

07 = 7 inch dia. Reel	
13 = 13 inch dia. Ree	è

10 = 10 inch dia. Reel 7D = 7 inch Dia. Reel with double quantity

(6) RESISTANCE VALUE

I Ω to 22 M Ω

There are $2\sim4$ digits indicated the resistance value. Letter R/K/M is decimal point, no need to mention the last zero after R/K/M, e.g. I K2, not I K20.

Detailed resistance rules are displayed in the table of "Resistance rule of global part number".

(7) DEFAULT CODE

Letter L is system default code for ordering only ^(Note)

Resistance rule of global part			
Resistance coding r	ule Example		
XRXX (Ι to 9.76 Ω)	R = ۱ Ω. R5 = ۱.5 Ω. 9R76 = 9.76 Ω		
XXRX (10 to 97.6 Ω)	ا OR = ۱۵ C 97R6 = 97.6 C		
XXXR (100 to 976 Ω)	$100R = 100 \Omega$		
XKXX (1 to 9.76 KΩ)	ا K = ۱,000 ۲ 9K76 = 9760 ۲		
XMXX (1 to 9.76 M Ω)	M = ,000,000 C 9M76= 9,760,000 C		

ORDERING EXAMPLE

The ordering code for an AF0402 chip resistor, value $100 \text{ K}\Omega$ with $\pm 1\%$ tolerance, supplied in 7-inch tape reel with 10Kpcs quantity is: AF0402FR-07100KL.

NOTE

- All our R-Chip products are RoHS compliant and Halogen free. "LFP" of the internal 2D reel label states "Lead-Free Process"
- 2. On customized label, "LFP" or specific symbol can be printed

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MARKING AF0201 / AF0	9402			
		No marking		
Fig. 1				
AF0603 / AF0	9805 / AF1206 / AF	-1210 / AF2010 / AF2512		
	ED	E-24 series: 3 digits, $\pm 5\%$, $\geq 10\Omega$		
Fig. 2 Val	ue=10 KΩ	First two digits for significant figure and 3rd digit for number of ze	eros	
AF0603				
	ШП			
		One short bar under marking letter		
rig. 3 val	ue – 24 52			
		E-96 series: 3 digits, ±1%	_	
Fig. 4 Valu	ue = 12.4 KΩ	First two digits for E-96 marking rule and 3rd letter for number of zeros		
AF0805 / AFI	206 / AFI2I0 / AF	F2010 / AF2512		
		Path E 24 and E 84 agrican 4 digits +1%		
Eig 5 Valu		First three digits for significant figure and 4th digit for number of :	zeros	
ALIZIO				
		E-24 series: 3 digits, $\pm 5\%$		
Fig. 6 Valu	le = 10 KΩ	First two digits for significant figure and 3rd digit for number of ze	eros	
		Both E-24 and E-96 series: 4 digits, $\pm 1\%$ First three digits for significant figure and 4th digit for number of :	zeros	
Fig. 7 Valu	$e = 10 K\Omega$			

ΝΟΤΕ

For further marking information, please see special data sheet "Chip resistors marking". Marking of AF series is the same as RC series



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CONSTRUCTION

The resistors are constructed on top of a high grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive glaze. The resistive glaze is covered by a lead-free glass. The composition of the glaze is adjusted to give the approximate required resistance value and laser trimming of this resistive glaze achieves the value within tolerance. The whole element is covered by a protective overcoat. Size 0603 and bigger is marked with the resistance value on top. Finally, the two external terminations (Ni / matte tin) are added. See fig.8

DIMENSIONS

Table I For outlines see fig. 8

TYPE	L (mm)	W (mm)	H (mm)	l⊨(mm)	l2 (mm)
AF0201	0.60±0.03	0.30±0.03	0.23±0.03	0.10±0.05	0.15±0.05
AF0402	1.00 ±0.05	0.50 ±0.05	0.32 ±0.05	0.20 ±0.10	0.25 ±0.10
AF0603	1.60 ±0.10	0.80 ±0.10	0.45 ±0.10	0.25 ±0.15	0.25 ±0.15
AF0805	2.00 ±0.10	1.25 ±0.10	0.50 ±0.10	0.35 ±0.20	0.35 ±0.20
AF1206	3.10 ±0.10	1.60 ±0.10	0.55 ±0.10	0.45 ±0.20	0.40 ±0.20
AF1210	3.10±0.10	2.60±0.15	0.50±0.10	0.45±0.15	0.50±0.20
AF1218	3.10±0.10	4.60±0.10	0.55±0.10	0.45±0.20	0.40±0.20
AF2010	5.00±0.10	2.50±0.15	0.55±0.10	0.55±0.15	0.50±0.20
AF2512	6.35±0.10	3.10±0.15	0.55±0.10	0.60±0.20	0.50±0.20

ELECTRICAL CHARACTERISTICS

Table 2 **CHARACTERISTICS** Max. Max. Dielectric TYPE Operating **RESISTANCE RANGE Temperature Coefficient** Withstanding Working Overload **Temperature Range** of Resistance Voltage Voltage Voltage \pm 5% (E24), I Ω to IOM Ω $|\Omega \le R \le |0\Omega|$, -|00/+350 ppm/°C AF0201 \pm 1% (E24/E96), 1 Ω to 10M Ω -55°C to +125°C 25 V 50 V 50 V $10\Omega < R \le 10M\Omega$, ±200 ppm/°C Zero Ohm Jumper < 0.05Ω AF0402 50 V 100 V 100 V $I \Omega \leq R \leq I0 \Omega$, ±200 ppm/°C AF0603 $\pm5\%$ (E24), I Ω to 22 M Ω 100 V 75 V 150 V ±1% (E24/E96), 1 Ω to 10 MΩ $10 \Omega < R \le 10 M\Omega$, $\pm 100 \text{ ppm/°C}$ AF0805 150 V 300 V 300 V Zero Ohm Jumper < 0.05 Ω $10 \text{ M}\Omega < \text{R} \le 22 \text{ M}\Omega, \pm 200 \text{ ppm/°C}$ AF1206 200 V 400 V 500 V -55 °C to +155 °C AF1210 200 V 500 V 500 V ±5% (E24), IΩ to I0MΩ AF1218 200 V 500 V 500 V IΩ≤ R≤ I0Ω, ±200 ppm/°C ±1% (E24/E96), IΩ to IOM AF2010 200 V 500 V 500 V $10\Omega < R \le 10M\Omega, \pm 200 \text{ ppm/}^{\circ}C$ Zero Ohm Jumper < 0.05Ω AF2512 200V 500V 500V



OUTLINES



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MLB206_2

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles of AF-series is the same as RC-series. Please see the special data sheet "Chip resistors mounting".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PACKING STYLE	REEL DIMENSION	AF0201	AF0402	AF0603/0805/ 1206	AF1210	AFI218/2010/ 2512
Paper taping reel (R)	7" (178 mm)	10,000/20,000	10,000/20,000	5,000	5,000	
	10" (254 mm)		20,000	10,000		
	13" (330 mm)	50,000	50,000	20,000	20,000	
Embossed taping reel (K)	7" (178 mm)					4,000

Р

ΝΟΤΕ

I. For paper/embossed tape and reel specification/dimensions, please see the special data sheet "Chip resistors packing".

FUNCTIONAL DESCRIPTION

OPERATING TEMPERATURE RANGE AF0201 Range: -55 °C to + 125 °C AF0402 - AF2512 Range: -55 °C to + 155 °C

POWER RATING

Each type rated power at 70 °C: AF0201=1/20W (0.05W) AF0402=1/16 W (0.0625W) AF0603=1/10 W (0.1W) AF0805=1/8 W (0.125W) AF1206=1/4 W (0.25W) AF1210=1/2W (0.5W) AF1218=1W AF2010=3/4W (0.75W) AF2512=1W

(%P_{rated}) 100 AF0402 - AF2512 50 AF0201 0+ -55 50 70 ò 100 125 155 °C) T_{amb} (**Fig. 7** Maximum dissipation (P_{max}) in percentage of rated power as a function of the operating ambient temperature (T_{amb})

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

 $V = \sqrt{(P \times R)}$

Where

V = Continuous rated DC or AC (rms) working voltage (V)

P = Rated power (W)

 $R = Resistance value (\Omega)$



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TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature Coefficient of	IEC 60115-1 4.8	At +25/–55 °C and +25/+125 °C	Refer to table 2
Resistance		Formula:	
(T.C.R.)		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$	
		Where t ₁ =+25 °C or specified room temperature	
		t_2 =–55 °C or +125 °C test temperature	
		R _I =resistance at reference temperature in ohms	
		R_2 =resistance at test temperature in ohms	
Life/Endurance	IEC 60115-1 4.25 MIL-STD-202 Method 108	At 70±2 °C for 1,000 hours, RCWV applied for 1.5 hours on, 0.5 hour off, still air required	±(1.0%+0.05 Ω) <100 mΩ for Jumper
High Temperature Exposure/ Endurance at Upper Category Temperature	MIL-STD-202 Method 108	1,000 hours at 155±5 °C, unpowered	\pm (1.0%+0.05 Ω) for 1% tol. \pm (1.0%+0.05 Ω) for 5% tol. <100 mΩ for Jumper
Moisture Resistance	MIL-STD-202 Method 106	Each temperature / humidity cycle is defined at 8 hours, 3 cycles / 24 hours for 10d. with 25 °C / 65 °C 95% R.H, without steps 7a & 7b, unpowered	$\pm (0.5\% + 0.05 \ \Omega)$ for 1% tol. $\pm (1.0\% + 0.05 \ \Omega)$ for 5% tol. <100 m Ω for Jumper
		Parts mounted on test-boards, without condensation on parts	
Thermal Shock	MIL-STD-202 Method 107	_55 / +125 ℃	±(0.5%+0.05 Ω) for 1% tol.
		Number of cycles required is 300. Devices unmounted	\pm (1%+0.05 Ω) for 5% tol. <100 mΩ for lumper
		Maximum transfer time is 20 seconds. Dwell time is 15 minutes	
Short Time Overload	IEC60115-14.13	2.5 times of rated voltage or maximum overload voltage whichever is less for 5 seconds at room temperature	±(1.0%+0.05 Ω) No visible damage
Bending	IEC 60115-1 4.33 IEC 60068-2-21	Chips mounted on a 90 mm glass epoxy resin PCB (FR4)	±(1.0%+0.05 Ω) <100 mΩ for lumper
		Bending: 0201/0402: 5 mm 0603/0805: 3 mm 1206 & above: 2 mm	No visible damage
		Bending time: 60±5 seconds	



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TEST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Biased Humidity (steady state)	IEC 60115-1 4.37	Steady state for 1,000 hours at 40°C / 95% R.H. RCWV applied for 1.5 hours on and 0.5 hour off	±(3.0%+0.05 Ω)	
Solderability				
- Resistance to	IEC 60115-1 4.18	Condition B, no pre-heat of samples	$\pm(0.5\%+0.05~\Omega)$ for 1% tol.	
Soldering Heat	MIL-STD-202 Method 215	Lead-free solder, 260±5 °C, 10±1 seconds immersion time	\pm (1.0%+0.05 Ω) for 5% tol. <50 mΩ for Jumper	
		Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	No visible damage	
- Wetting	J-STD-002	Electrical test not required	Well tinned (≥95% covered)	
		Magnification 10X	No visible damage	
		SMD conditions:		
		(a) Method B, aging 4 hours at 155 ℃ dry heat, lead-free solder bath at 245 ℃		
		(b) Method B, dipping at 215 $^\circ \! C$ for 3 seconds		
FOS	ASTM-B-809-95	Sulfur (saturated vapor) 1,000 hours, 60±2 °C,	±(1.0%+0.05 Ω)	
		91-93% R.H., unpowered		



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REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version I	Sep. 27, 2013	-	- Size 0201/1210/1218/2010/2512 extend
Version 0	Jan 07, 2011	-	- First issue of this specification

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